TOSHIBA Diode Silicon Epitaxial Schottky Barrier Type

# **1SS373**

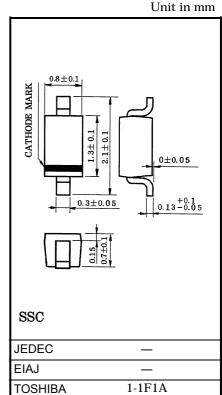
High Speed Switching Application

- Small package
- Low forward voltage: V<sub>F</sub> = 0.23V (typ.) @I<sub>F</sub> = 5mA

### Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit	
Maximum (peak) reverse Voltage	V <sub>RM</sub>	15	V	
Reverse voltage	V <sub>R</sub>	10	V	
Maximum (peak) forward current	I <sub>FM</sub>	200	mA	
Average forward current	Ι <sub>Ο</sub>	100	mA	
Surge current (10ms)	I <sub>FSM</sub>	1	А	
Power dissipation	P *	150	mW	
Junction temperature	Тј	125	°C	
Storage temperature range	T <sub>stg</sub>	-55~125	°C	
Operating temperature range	T <sub>opr</sub>	-40~100	°C	

\* Mounted on a glass epoxy circuit board of  $20 \times 20$  mm Pad dimension of  $4 \times 4$  mm.



Weight: 1.9mg

### **Electrical Characteristics (Ta = 25°C)**

Characteristic	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V <sub>F (1)</sub>	-	I <sub>F</sub> = 1mA	_	0.18	_	
	V <sub>F (2)</sub>	_	I <sub>F</sub> = 5mA	_	0.23	0.30	V
	V <sub>F (3)</sub>	_	I <sub>F</sub> = 100mA	_	0.35	0.50	
Reverse current	I <sub>R</sub>	_	V <sub>R</sub> = 10V	_	_	20	μA
Total capacitance	CT	_	V <sub>R</sub> = 0, f = 1MH <sub>z</sub>		20	40	pF

## Equivalent Circuit (Top View)

### Marking





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